

Serial Nr.: 09/209,634
Art Unit: 2811



UPA-98165

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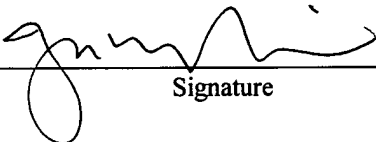
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

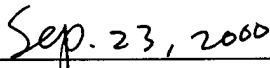
Serial No.: **09/209,634** Examiner: **Luan Thai**
Inventor: **Fang-Jun Leu, Rong-Shen Lee, Hsin-Chien Huang,**
Randy Hsiao-Yu Lo and Chiang-Han Day
Filed: **December 10, 1998** Art Unit: **2811**
Title: **Flip-Chip Ball Grid Array Package With A Heat Slug**

Certificate of Mailing

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Box Drawing Review Branch, Assistant Commissioner for Patents, Washington, D.C. 20231, on the date shown below.



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SUBMISSION OF FORMAL DRAWINGS

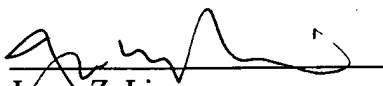
Assistant Commissioner For Patents
Washington, D.C. 20231

Attn.: Chief Draftsperson

Sir:

Enclosed are **ten** sheets of the formal drawings for FIGs. **1-8** for correcting informalities and filing in the above-identified U.S. patent application.

Respectfully submitted,



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